

MSASC25H45K MSASC25H45KR

Features

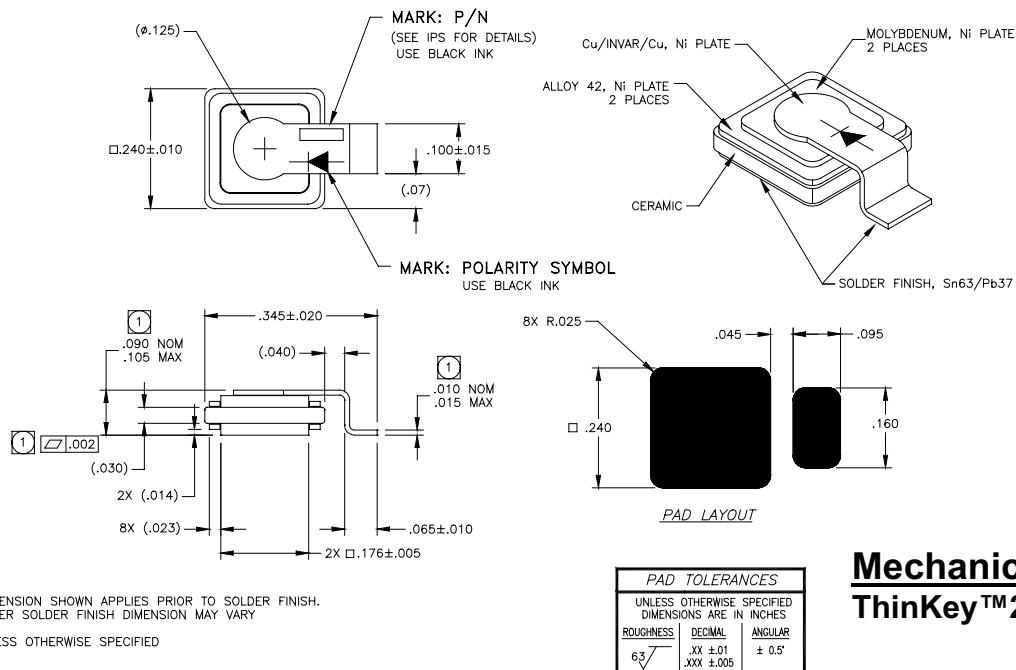
- Tungsten/Platinum schottky barrier for very low VF
- Oxide passivated structure for very low leakage currents
- Guard ring protection for increased reverse energy capability
- Epitaxial structure minimizes forward voltage drop
- Hermetically sealed, low profile ceramic surface mount power package
- Low package inductance
- Very low thermal resistance
- Available as standard polarity (strap is anode:MSASC25H45K) and reverse polarity (strap is cathode:MSASC25H45KR)
- TXV-level (MSASC25H45KV) or S-level (MSASC25H45KS) screening i.a.w. Microsemi Internal Procedure PS11.50 available

**45 Volts
25 Amps**

**LOW VOLTAGE
DROP SCHOTTKY
DIODE**

Maximum Ratings @ 25°C (unless otherwise specified)

DESCRIPTION	SYMBOL	MAX.	UNIT
Peak Repetitive Reverse Voltage	V _{RRM}	45	Volts
Working Peak Reverse Voltage	V _{RWM}	45	Volts
DC Blocking Voltage	V _R	45	Volts
Average Rectified Forward Current, T _c ≤ 145°C derating, forward current, T _c ≥ 145°C	I _{F(ave)} dI _F /dT	25 (3.3)	Amps Amps/°C
Nonrepetitive Peak Surge Current, t _p = 8.3 ms, half-sinewave	I _{FSM}	280	Amps
Peak Repetitive Reverse Surge Current, t _p = 1μs, f= 1kHz	I _{RRM}	2	Amp
Junction Temperature Range	T _j	-55 to +150	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Thermal Resistance, Junction to Case:	θ _{JC}	0.85 0.95	°C/W
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Mechanical Outline ThinKey™2

Electrical Parameters

DESCRIPTION	SYMBOL	CONDITIONS	MIN	TYP.	MAX	UNIT
Reverse (Leakage) Current	IR	VR= 45 Vdc, Tc= 25°C		300	1000	µA
	IR	VR= 45 Vdc, Tc= 125°C		100	150	mA
Forward Voltage pulse test, pw= 300 µs d/c≤ 2%	VF	IF= 5A, Tc= 25°C		375	475	mV
	VF	IF= 10A, Tc= 25°C		430	520	mV
	VF	IF= 20A, Tc= 25°C		510	610	mV
	VF	IF= 50A, Tc= 25°C		740		mV
	VF	IF= 10A, Tc= -55°C		480	580	mV
	VF	IF= 10A, Tc= 125°C		360		mV
Junction Capacitance	Cj	VR= 10 Vdc		525	600	pF
	Cj	VR= 5 Vdc		725		pF
Breakdown Voltage	BVR	IR= 1 mA, Tc= 25°C		55		V
		IR= 1 mA, Tc= -55°C	45	50		V

VF typical vs. IF

